

In re application of

Confirmation No. 5067

Mizuki NAGAI et al.

Docket No. 2003\_1338

Serial No. 10/664,078

Group Art Unit 1753

Filed September 17, 2003

Examiner Edna Wong

COPPER-PLATING LIQUID, PLATING METHOD AND PLATING APPARATUS

Mail Stop: Amendment

## **RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In reply to the Notice of Non-Compliant Amendment dated July 21, 2005, please amend the present application as follows: